Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
11	11	(("5196371") or ("6593220") or ("5181984") or ("6150193") or ("6469897") or ("6479887") or ("20040005770") or ("20040165362") or ("20040032020") or ("20040077109") or ("20040142058")).PN.	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	OFF	2005/03/02 13:15
L2	64	(((((transfer adj molding) and needle) and dispenser) and encapsulant ) (((((438/118,127) or (257/737,738,782,783,787)). CCLS.) and @ad<"20020722") not micron.as. )) and @pd>"20041109"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/03/02 13:18
S1	154	(((((transfer adj molding) and needle) and dispenser) and encapsulant ) (((((438/118,127) or (257/737,738,782;783,787)). CCLS.) and @ad<"20020722") not micron.as. )) and @pd>"20040608"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2005/03/02 13:18
S2		(("5196371") or ("6658314") or ("20040165362") or ("20040142058")).PN.	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	OFF	2004/11/05 08:40
S3	7	(("6017776") or ("6048755") or ("6049129") or ("6177723") or ("6214645") or ("6246124") or ("6329224")) PN	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	OFF	2005/03/02 13:14
S4	5489	((438/118,127) or (257/737,738, 782,783,787)).CCLS.	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	OFF	2004/01/09 10:57
S5	5007	(((438/118,127) or (257/737,738, 782,783,787)).CCLS.) and @ad<"20020722"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 10:59
S6	4634	((((438/118,127) or (257/737,738, 782,783,787)).CCLS.) and @ad<"20020722") not micron.as.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/06/01 10:20
S7	4829	"chip scale package" CSP	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 11:00
S8	2900	solder adj mask	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 11:00
S9.	231	("chip scale package" CSP) and (solder ad) mask)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 10:59

S10	2763	"chip scale package" CSP	EPO; JPO; DERWENT	OR	OFF	2004/01/09 11:00
S11	1023	solder adj mask	EPO; JPO; DERWENT	OR	OFF	2004/01/09 11:00
S12	549	(((((438/118,127) or (257/737, 738,782,783,787)).CCLS.) and @ad<"20020722") not micron.as.) and ("chip scale package" CSP)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:53
S13	342	(((((438/118,127) or (257/737, 738,782,783,787)).CCLS.) and @ad<"20020722") not micron.as.) and (solder adj mask)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 11:00
S14	18	("chip scale package" CSP) and (solder adj mask)	EPO; JPO; DERWENT	OR	OFF	2004/01/09 11:02
S15	6	"888674"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 11:03
S16	1	("6486005").PN.	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	OFF	2004/01/09 11:05
S17	27	((grigg-ford-b grigg-ford reeder-william-j reeder-william).in. ) not micron:as.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 11:05
S18	59	(grigg-ford-b grigg-ford reeder-william).in.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 11:08
S19	. 29	(("5173220") or ("5259793") or ("5264061") or ("5278442") or ("5336931") or ("5484314") or ("5574310") or ("5705117") or ("5714800") or ("5714802") or ("5719440") or ("5767443") or ("5793116") or ("5866949") or ("5920118") or ("5965933") or ("5977640") or ("5994166") or ("5999413") or ("6013946") or ("6091140") or ("6124407") or ("6222263") or ("6372552") or ("6348664") or ("6489183")).PN.	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	OFF	2004/01/09:11:08
S20	200	(("chip scale package" CSP) and (solder adj mask)) and @ad<"20020722"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 11:12
S21	188	((("chip scale package" CSP) and (solder adj mask)) and @ad<"20020722") not micron.as	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 11:12

S22	828	((((((438/118,127) or (257/737,	US-PGPUB;	OR	OFF	2004/01/09 11:15
	55	738,782,783,787)).CCLS.) and @ad<"20020722") not micron.as.) and ("chip scale package" CSP)) ((((((438/118,127) or (257/737, 738,782,783,787)).CCLS.) and @ad<"20020722") not micron.as.) and (solder adj mask))	USPAT; IBM_TDB	·		
S23	0	(asamura-kiyoshi);in.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:20
S24	61	(yaguchi-akihiro).in.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:20
S25	0	"semiconductor adj device".ti.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:21
S26	55	"semiconductor device".ti. and ((yaguchi-akihiro).in.)	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:21
S27	46	("semiconductor device".ti. and ((yaguchi-akihiro).in.)) and (kitano-makoto).in.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:22
S28	6	(("semiconductor device".ti. and ((yaguchi-akihiro).in.)) and (kitano-makoto).in.) and (kumazawa-tetsuo).in.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:22
S29	48	((yaguchi-akihiro).in.) and (kitano-makoto).in.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:22
S30	7	(((yaguchi-akihiro).in.) and (kitano-makoto).in.) and (kumazawa-tetsuo).in.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:22
S31	0	"97/10865"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:23
S32	1	"97/01865"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/09 13:52

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S33	68	(("3838984") or ("5045921") or	US-PGPUB;	OR	OFF	2004/01/09 13:59
i		("5409865") or ("5420460") or	USPAT;			
		("5600180") or ("5604379") or	USOCR;			
		("5608265") or ("5616958") or	IBM_TDB			
		("5640047") or ("5650593") or				
		("5656863") or ("5663593") or				
		("5663594") or ("5672912") or				
		("5859475") or ("5270267") or				
	ļ	("5677566") or ("5715593") or		l		
		("5785538") or ("5821605") or				
		("5863805") or ("5879964") or				1
		("5880520") or ("5900582") or				
1		("5904500") or ("5907186") or		1		1
		("5929514") or ("5933708") or		,		
		("5951804") or ("5998865") or	1			İ
ì		("6013109") or ("6013535") or				
		("6020692") or ("6028356") or				
		("6107683") or ("6127833") or		l		
1		("6143581") or ("6166443") or	-			
		("6169329") or ("6204093") or				
		("6210992") or ("5849608") or				
ŀ		("5920118") or ("6181569") or				
		("6287893") or ("6326698") or				
		("6376279") or ("6165885") or				
	1	("6245594") or ("6426241") or				
		("6284566") or ("6359221") or				
		("6441483") or ("6465734") or				
ł		("6475629") or ("6507107") or				
		("6514847") or ("6538309") or				
1		("6555923") or ("6573612") or	-			
		("6577004") or ("6590297") or	ļ			
İ		("6671951") or ("6432746") or				
		("6577015") or ("6630730") or			:	
1		("6653173") or ("6664139")).PN.		1	1	
	: :::::::::::::::::::::::::::::::::::::					
S34	516	encapsulation and "solder mask"	US-PGPUB;	OR	OFF	2004/01/09 13:53
			USPAT;			
			IBM_TDB			
S35	443	(encapsulation and "solder mask")	US-PGPUB;	OR	OFF	2004/01/09 13:53
333	1	and @ad<"20020722" not micron.	USPAT;	"	"'	
		and wad 20020722 not micron.	IBM_TDB			
S36	65	encapsulation with "solder mask"	US-PGPUB;	OR	OFF	2004/01/09 13:53
			USPAT;			
			IBM_TDB			
S37	55	(encapsulation with "solder mask")	US-PGPUB;	OR	OFF	2004/01/09 13:54
33/	35	and @ad<"20020722" not micron.	USPAT;		511	200 1,02,05 13.51
		_	IBM_TDB			
L	]	as.	1011_100	1	1	

S45	325	(transfer adj molding) and needle	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/13 11:02
S46	29	((transfer adj molding) and needle) and dispenser	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/01/13 11:02
S47	4	(((transfer adj molding) and needle) and dispenser) and encapsulant	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/06/01 10:20
S48	4	(((transfer adj molding) and needle) and dispenser) and encapsulant	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/06/01 10:20
S49	·4803	((((438/118,127) or (257/737,738, 782,783,787)).CCLS.) and @ad<"20020722") not micron.as.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/06/01 10:20
S50	152	(((((transfer adj molding) and needle) and dispenser) and encapsulant ) (((((438/118,127) or (257/737,738,782,783,787)). CCLS.) and @ad<"20020722") not micron.as. )) and @pd>"20040120"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/11/05 08:40
S51	0	10/370755	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/06/01 10:24
S52	0	10/672098	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/06/01 10:24
S53	1	09/590527	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/06/01 10:41
S54	1	"09590621"	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/06/01 10:39
S55	2	10/191424	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/06/01 10:40
S56	1	10/641471	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/06/01 10:40
S57	1	10/642908	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2004/06/01 10:40
S58	4	(("5181984") or ("6150193") or ("6469897") or ("6479887")).PN.	US-PGPUB; USPAT; USOCR; IBM_TDB	OR	OFF	2005/03/01 10:41